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Halvledarkomponenter – Mekaniska och klimatiska provningsmetoder – Del 3: Utvändig okulärbesiktning

*Semiconductor devices –
Mechanical and climatic test methods –
Part 3: External visual examination*

Som svensk standard gäller europastandarden EN 60749-3:2017. Den svenska standarden innehåller den officiella engelska språkversionen av EN 60749-3:2017.

Nationellt förord

Europastandarden EN 60749-3:2017

består av:

- **europastandardens ikraftsättningsdokument**, utarbetat inom CENELEC
- **IEC 60749-3, Second edition, 2017 - Semiconductor devices - Mechanical and climatic test methods - Part 3: External visual examination**

utarbetad inom International Electrotechnical Commission, IEC.

Tidigare fastställd svensk standard SS-EN 60749-3, utgåva 1, 2003, gäller ej fr o m 2020-04-07.

Standarder underlättar utvecklingen och höjer elsäkerheten

Det finns många fördelar med att ha gemensamma tekniska regler för bl a mätning, säkerhet och provning och för utförande, skötsel och dokumentation av elprodukter och elanläggningar.

Genom att utforma sådana standarder blir säkerhetsfordringar tydliga och utvecklingskostnaderna rimliga samtidigt som marknadens acceptans för produkten eller tjänsten ökar.

Många standarder inom elområdet beskriver tekniska lösningar och metoder som åstadkommer den elsäkerhet som föreskrivs av svenska myndigheter och av EU.

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SEK samordnar svenska intressenters medverkan i SEKs tekniska kommittéer och stödjer svenska experters medverkan i internationella och europeiska projekt.

Stora delar av arbetet sker internationellt

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Arbetet i de tekniska kommittéerna är öppet för alla svenska organisationer, företag, institutioner, myndigheter och statliga verk. Den årliga avgiften för deltagandet och intäkter från försäljning finansierar SEKs standardiseringsverksamhet och medlemsavgift till IEC och CENELEC.

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Du som vill dra nytta av dessa möjligheter är välkommen att kontakta SEKs kansli för mer information.

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English Version

**Semiconductor devices - Mechanical and climatic test methods -
Part 3: External visual examination
(IEC 60749-3:2017)**

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 3: Examen visuel
externe
(IEC 60749-3:2017)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 3: Äußere Sichtprüfung
(IEC 60749-3:2017)

This European Standard was approved by CENELEC on 2017-04-07. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.



European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

European foreword

The text of document 47/2345/FDIS, future edition 2 of IEC 60749-3, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60749-3:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2018-01-07
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-04-07

This document supersedes EN 60749-3:2002.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 60749-3:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated :

IEC 60749-9	NOTE	Harmonized as EN 60749-9.
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Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1	-
IEC 62483	-	Environmental acceptance requirements for tin whisker susceptibility of tin and tin alloy surface finishes on semiconductor devices	-	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 3: External visual examination****FOREWORD**

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 60749-3 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2002. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) reference to the need for ESD protection;
- b) inclusion of information on the phenomenon of tin whiskers;
- c) inclusion of an optional report form/checklist.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2345/FDIS	47/2370/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 3: External visual examination

1 Scope

The purpose of this part of IEC 60749 is to verify that the materials, design, construction, markings, and workmanship of a semiconductor device are in accordance with the applicable procurement document. External visual inspection is a non-destructive test and applicable for all package types. The test is useful for qualification, process monitor, or lot acceptance.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61340-5-1, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC 62483, *Environmental acceptance requirements for tin whisker susceptibility of tin and tin alloy surface finishes on semiconductor devices*